

3SK296

Silicon N-Channel Dual Gate MOS FET

REJ03G0815-0300 (Previous ADE-208-388A) Rev.3.00 Aug.10.2005

Application

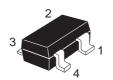
UHF RF amplifier

Features

- Low noise figure. NF = 2.0 dB Typ. at f = 900 MHz
- Capable of low voltage operation

Outline

RENESAS Package code: PTSP0004ZA-A (Package name: CMPAK-4)



- 1. Source
- 2. Gate1
- 3. Gate2
- 4. Drain

Note: Marking is "ZQ-"

Attention:

This device is very sensitive to electro static discharge.

It is recommended to adopt appropriate cautions when handling this transistor.

Absolute Maximum Ratings

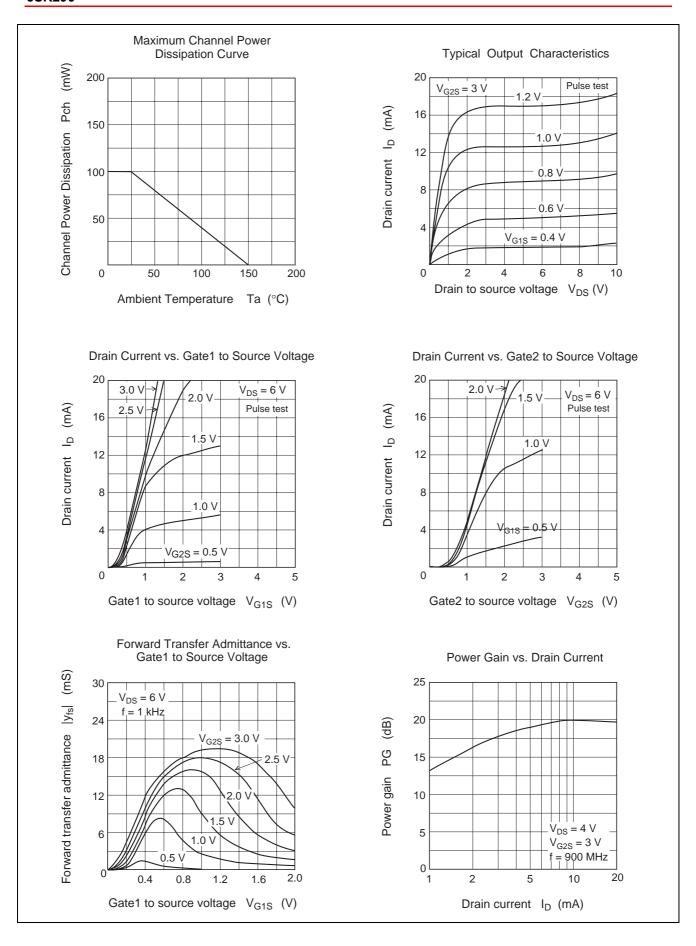
 $(Ta = 25^{\circ}C)$

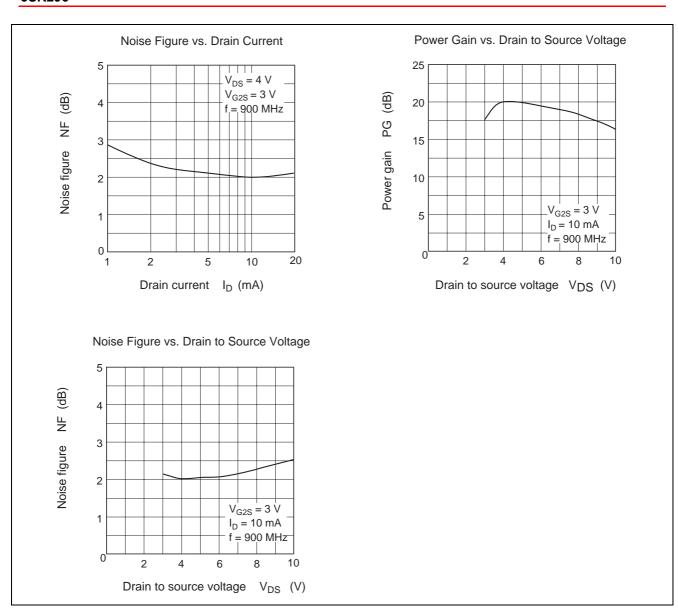
Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DS}	12	V	
Gate 1 to source voltage	V_{G1S}	±8	V	
Gate 2 to source voltage	V _{G2S}	±8	V	
Drain current I _D		25	mA	
Channel power dissipation	Pch	100	mW	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

Electrical Characteristics

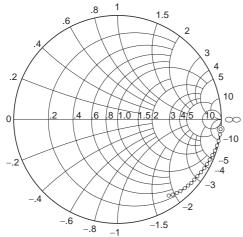
 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSX}$	12	_	_	V	$I_D = 200 \mu\text{A}$, $V_{G1S} = -3 \text{V}$,
						$V_{G2S} = -3 \text{ V}$
Gate 1 to source breakdown voltage	$V_{(BR)G1SS}$	±8			V	$I_{G1} = \pm 10 \mu A, V_{G2S} = V_{DS} = 0$
Gate 2 to source breakdown voltage	$V_{(BR) G2SS}$	±8	_	_	V	$I_{G2} = \pm 10 \mu A, V_{G1S} = V_{DS} = 0$
Gate 1 cutoff current	I _{G1SS}	_	_	±100	nA	$V_{G1S} = \pm 6 \text{ V}, V_{G2S} = V_{DS} = 0$
Gate 2 cutoff current	I _{G2SS}	_	_	±100	nA	$V_{G2S} = \pm 6 \text{ V}, V_{G1S} = V_{DS} = 0$
Drain current	I _{DS(on)}	0.5	_	10	mA	$V_{DS} = 6 \text{ V}, V_{G1S} = 0.5 \text{V},$
						V _{G2S} = 3 V
Gate 1 to source cutoff voltage	$V_{G1S(off)}$	-0.5	_	+0.5	V	$V_{DS} = 10 \text{ V}, V_{G2S} = 3\text{V},$
						I _D = 100 μA
Gate 2 to source cutoff voltage	$V_{G2S(off)}$	0		+1.0	V	$V_{DS} = 10 \text{ V}, V_{G1S} = 3\text{V},$
						I _D = 100 μA
Forward transfer admittance	y _{fs}	16	20.8	_	mS	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{V},$
						$I_D = 10 \text{ mA}, f = 1 \text{ kHz}$
Input capacitance	Ciss	1.2	1.5	2.2	pF	$V_{DS} = 6 \text{ V}, V_{G2S} = 3 \text{V},$
Output capacitance	Coss	0.6	0.9	1.2	pF	I _D = 10 mA, f = 1 MHz
Reverse transfer capacitance	Crss	_	0.01	0.03	pF	
Power gain	PG	16	19.5	_	dB	V _{DS} = 4 V, V _{G2S} = 3V,
Noise figure	NF		2.0	3	dB	I _D = 10 mA, f = 900 MHz





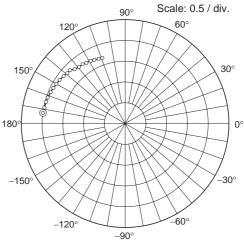
S11 Parameter vs. Frequency



 $\begin{array}{cccc} \text{Condition:} & \text{V}_{DS}\text{= 4 V} \text{ , V}_{G2S}\text{= 3 V} \\ & \text{I}_{D}\text{= 10 mA} \text{ , Zo = 50 } \Omega \\ \text{100 to 1000 MHz (50 MHz step)} \end{array}$

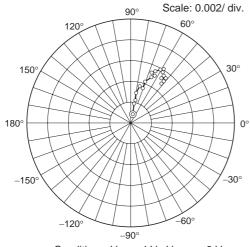
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S21 Parameter vs. Frequency



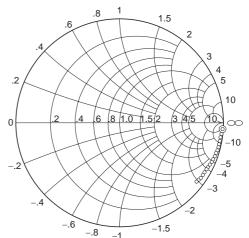
Condition: V_{DS} = 4 V , V_{G2S} = 3 V I_{D} = 10 mA , Z_{O} = 50 Ω 100 to 1000 MHz (50 MHz step)

S12 Parameter vs. Frequency



Condition: V_{DS} = 4 V , V_{G2S} = 3 V I_{D} = 10 mA , Zo = 50 Ω 100 to 1000 MHz (50 MHz step)

S22 Parameter vs. Frequency



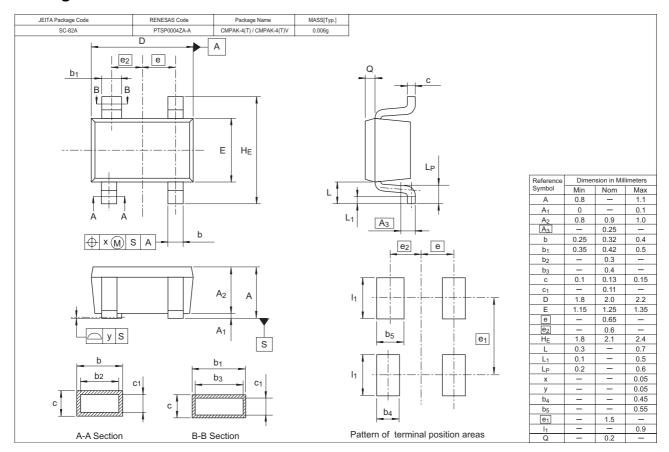
Condition: $V_{DS} = 4 \text{ V}$, $V_{G2S} = 3 \text{ V}$ I $_{D} = 10 \text{ mA}$, $Z_{O} = 50 \Omega$ 100 to 1000 MHz (50 MHz step)

S Parameter

 $(V_{DS} = 4 \text{ V}, V_{G2S} = 3 \text{ V}, I_D = 10 \text{ mA}, Z_O = 50 \Omega)$

Freq.	S11		S21		S [,]	12	S22	
(MHz)	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.
100	0.999	-6.1	1.98	172.2	0.00094	79.2	0.989	-4.2
150	0.998	-9.1	1.97	168.4	0.00189	80.4	0.987	-6.1
200	0.992	-11.9	1.96	165.0	0.00230	79.5	0.986	-7.9
250	0.988	-14.8	1.96	161.0	0.00286	79.9	0.984	-9.8
300	0.985	-17.9	1.94	157.1	0.00364	75.2	0.981	-11.5
350	0.976	-20.6	1.92	153.7	0.00353	71.8	0.978	-13.4
400	0.971	-23.2	1.91	149.9	0.00419	70.7	0.975	-15.2
450	0.964	-26.3	1.88	146.8	0.00495	65.5	0.972	-17.2
500	0.961	-29.1	1.87	142.8	0.00509	62.7	0.968	-19.1
550	0.951	-32.2	1.86	139.4	0.00530	66.6	0.963	-20.8
600	0.949	-35.0	1.86	136.1	0.00550	63.8	0.960	-22.8
650	0.935	-37.6	1.81	132.9	0.00601	58.2	0.956	-24.5
700	0.933	-40.5	1.78	129.4	0.00582	60.6	0.950	-26.3
750	0.923	-42.9	1.77	125.7	0.00572	58.5	0.945	-28.0
800	0.916	-45.8	1.75	122.6	0.00553	56.3	0.941	-29.9
850	0.908	-49.0	1.72	119.1	0.00514	56.3	0.936	-31.7
900	0.900	-51.2	1.70	115.8	0.00543	52.9	0.930	-33.4
950	0.890	-54.0	1.67	112.6	0.00506	52.4	0.924	-35.2
1000	0.876	-56.4	1.65	109.3	0.00469	51.9	0.919	-37.0

Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container		
3SK296ZQ-TL-E	3000	φ 178 mm Reel, 8 mm Emboss Taping		

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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Renesas Technology Korea Co., Ltd.Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea Tel: <82> 2-796-3115, Fax: <82> 2-796-2145

Renesas Technology Malaysia Sdn. Bhd. Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia Tel: <603> 7955-9390, Fax: <603> 7955-9510